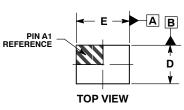
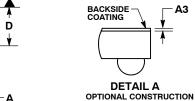


WLCSP6 0.85x1.17x0.40 CASE 567TL

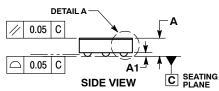
ISSUE O

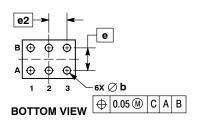
DATE 14 MAR 2017





NOTE 6



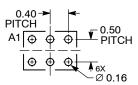


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 1 14.3M, 1994.
 2 CONTROLLING DIMENSION: MILLIMETERS.
 3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS
- 4. COPLANARITY APPLIES TO THE SPHERICAL
- CROWNS OF THE SOLDER BALLS.
 DIMENSION 6 IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
 6. BACKSIDE COATING IS OPTIONAL.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α			0.40	
A1	0.05	0.08	0.11	
АЗ	0.025 REF			
b	0.11	0.16	0.21	
D	0.80	0.85	0.90	
E	1.12	1.17	1.22	
е	0.50 BSC			
e2	0.40 BSC			

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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